For Immediate Release



WLCSP Test: Efficient High Volume Solution for Post-Saw Testing Multitest InWaferX for final test of singulated WLCSPs

Rosenheim (Germany), November 2017: Multitest's new InWaferX final test solution for singulated WLCSPs addresses the increased quality demand for automotive applications as these quality requirements are expanding to cost sensitive, high volume consumer applications. Based on the production proven InCarrier technology, InWaferX ensures highest efficiency and yield for lowest cost of test.

The InWaferX solution enables post saw testing of singulated WLCSPs detecting all production defects in true final test of singulated devices. In addition, the same process can be deployed for retest and RMA process handling. Both options significantly enhance the production quality of the shipped devices and substantially support the zero defect parts per million (ppm) efforts of the device makers. In addition the InWaferX is equipped with a full 6 side vision inspection capability for complete physical validation.

InWaferX combines high multisite testing with the highest positioning accuracy for best yield and 100% touch efficiency on the rectangular carrier trays. InWaferX supports the high daily output requirements in today's high volume manufacturing (HVM) environments.

Based on the well-established InCarrier / InStrip solution, the InWaferX supports full range temperature testing, as well as, MEMS/sensor testing. The InWaferX final test solution can be applied for WLCSPs from sawn film frame or tape and reel.

Andreas Bursian, Senior Director Innovation, comments: "We did extensive system validation on a production test floor and passed all requirements such as ESD, safety and operational conditions. Compared to the traditional wafer probing, the InWaferX test solution has proven to increase test throughput and outgoing device quality.

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To learn more about the Multitest InWaferX solution based on the InCarrier, please visit www.multitest.com/incarrier

About Multitest:

Multitest (headquartered in Rosenheim, Germany) is one of the world's leading manufacturers of semiconductor material handling equipment and interfaces for the testing and calibration of semiconductors and sensors. Multitest markets a broad portfolio of innovative and performance driven test handlers, contactors and ATE printed circuit boards. Multitest has more than 30 years of experience in the semiconductor industry, providing solutions to the automotive, consumer, communication, and sensor markets. Multitest is a company of Xcerra™ Corporation, which provides capital equipment, interface products, and services to the semiconductor, industrial, and electronics manufacturing industries. Xcerra Corporation offers a comprehensive portfolio of solutions and technologies, and a global network of strategically deployed applications and support resources. Additional information can be found at www.multitest.com and www.multitest.com and www.xcerra.com

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